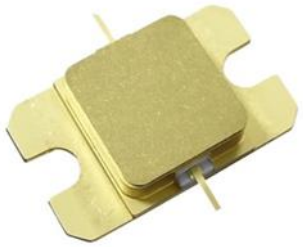
■ Features

- High Output Power: P_{5dB}=48.0dBm (Typ.)
- High Gain: GL=13.5dB (Typ.)
- High Power Added Efficiency: PAE=41% (Typ.)
- Broad Band: 6.4 to 7.2GHz
- Hermetically Sealed Package



■ Description

The SGK6472-60C is a high power GaN-HEMT that is internally matched for standard communication bands to provide optimum power and gain in a 50ohm system.

ABSOLUTE MAXIMUM RATING (Case Temperature T_c=25 deg.C)

Item	Symbol	Rating	Unit
Drain-Source Voltage	V_{DS}	26	V
Gate-Source Voltage	V_{GS}	-10	V
Total Power Dissipation	P_T	150	W
Storage Temperature	T_{stg}	-55 to +125	deg.C
Channel Temperature	T_{ch}	+250	deg.C
Case Temperature	T_c	-40 to +125	deg.C

RECOMMENDED OPERATING CONDITION

Item	Symbol	Condition	Limit	Unit
Drain-Source Voltage	V_{DS}		<=24	V
Forward Gate Current	I_{GF}	Rg=51ohm	<=8.8	mA
Reverse Gate Current	I_{GR}	Rg=51ohm	>=-4.6	mA
Channel Temperature	T_{ch}		<+193	deg.C

ELECTRICAL CHARACTERISTICS (Case Temperature T_c=25 deg.C)

Item	Symbol	Condition	Limit			Unit
			Min.	Typ.	Max.	
Saturated Drain Current	I_{DSS}	V_{DS}=10V, V_{GS}=0V	-	16.6	-	A
Trans Conductance	G_m	V_{DS}=24V, I_{DS}=1.92A	-	4.4	-	S
Pinch-off Voltage	V_P	V_{DS}=24V, I_{DS}=1.92mA	-2.5	-4.0	-5.5	V
Output Power at 5dB G.C.P.	P_{5dB}	VDS=24V(typ.) IDS(DC)=2.6A(typ.) f=6.4 to 7.2 GHz Vgs-constant	47.0	48.0	-	dBm
Linear Gain at Pin=26dBm	GL		11.0	13.5	-	dB
Drain Current at 5dB G.C.P.	I_{DSR}		-	6.4	7.0	A
Power Added Efficiency at 3dB G.C.P.	PAE		-	41	-	%
Gain Flatness	ΔG		-	-	1.6	dB
3rd Order Inter modulation Distortion	IM_3	f=6.4GHz, 7.2GHz Δf=10MHz, 2-tone Test Pout=32.0dBm (S.C.L.)	-40.0	-42.0	-	dBc
Thermal Resistance	R_{th}	Channel to Case (T_c=25deg.C, P_{diss}=62.4W)	-	1.3	1.5	deg.C/W
Channel Temperature Rise	ΔT_{ch}	(V_{DS} x I_{DSR} – Pout + Pin) x R_{th}	-	100	150	deg.C

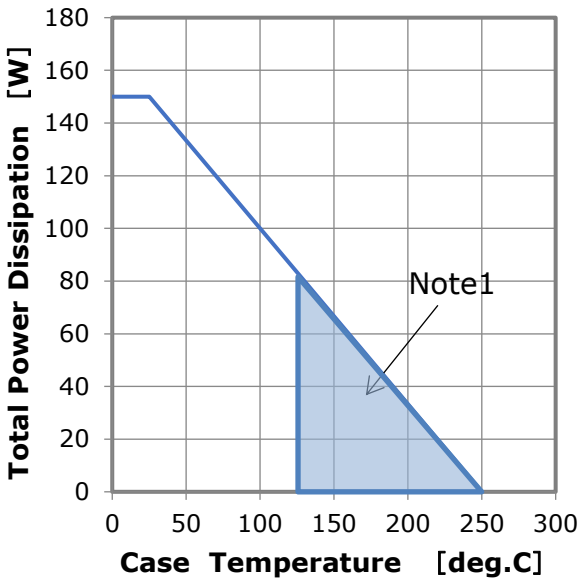
G.C.P. : Gain Compression Point, S.C.L. : Single Carrier Level

CASE STYLE	IBK	
RoHS Compliance	YES	
ESD [*1]	Class 2	2000V to <4000V

Note : [*1] Based on ANSI/ESDA/JEDEC JS-001-2012(C=100pF, R=1.5kohm)

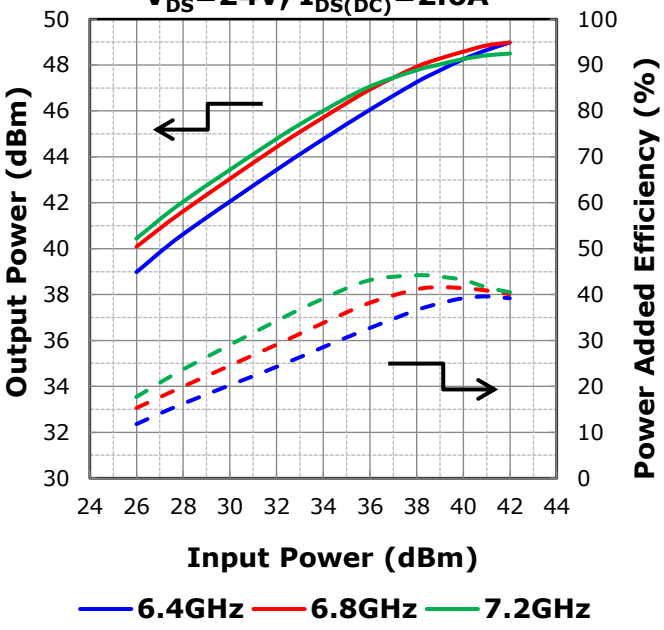
● RF Characteristics

Power Derating Curve

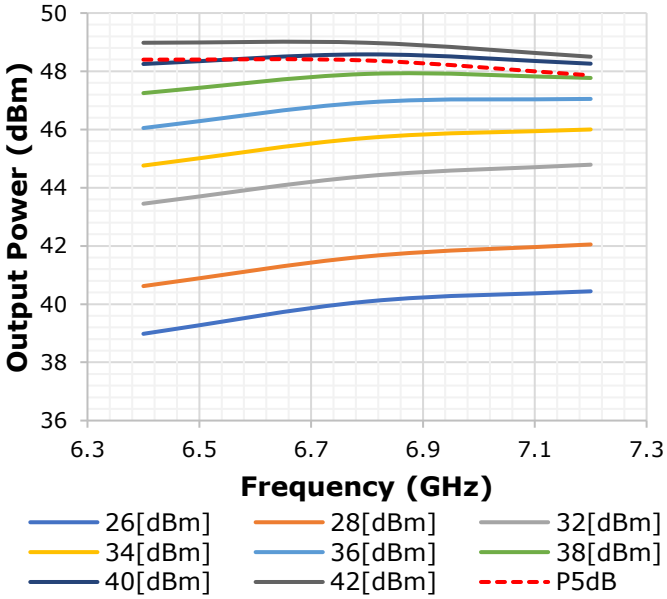


Note 1: Shaded area exceeds Maximum Case Operating Temperature (See Page1)

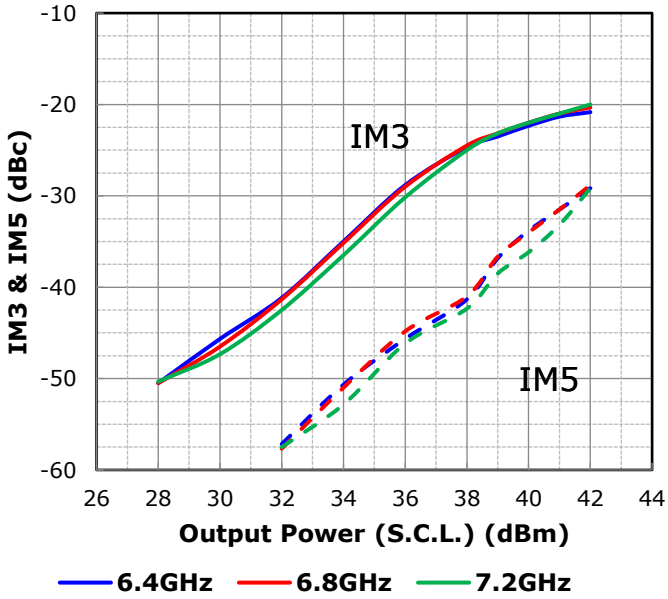
Output Power and Power Added Efficiency vs. Input Power
V_{DS}=24V, $I_{DS(DC)}$=2.6A



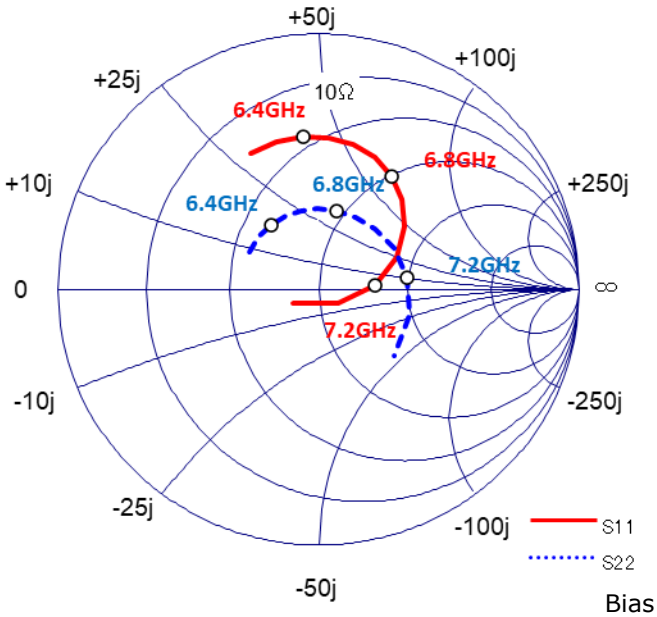
Output Power vs. Frequency
V_{DS}=24V, $I_{DS(DC)}$=2.6A

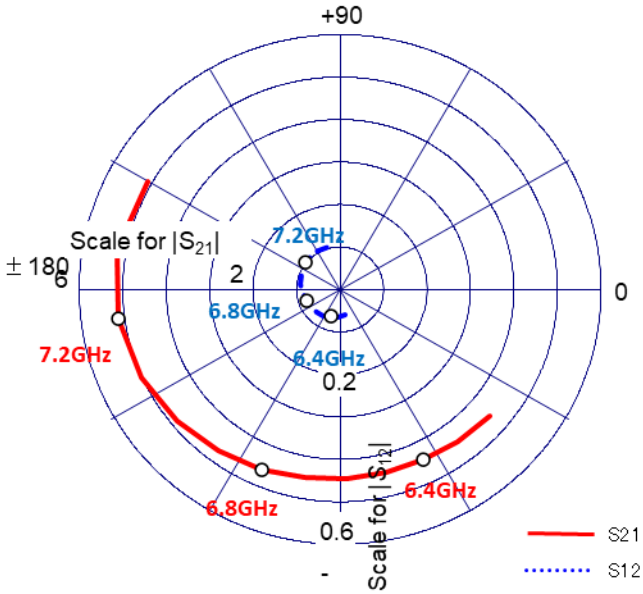


IMD vs. Output Power (S.C.L.)
V_{DS}=24V, $I_{DS(DC)}$=2.6A, Δf=10MHz



● S-Parameter

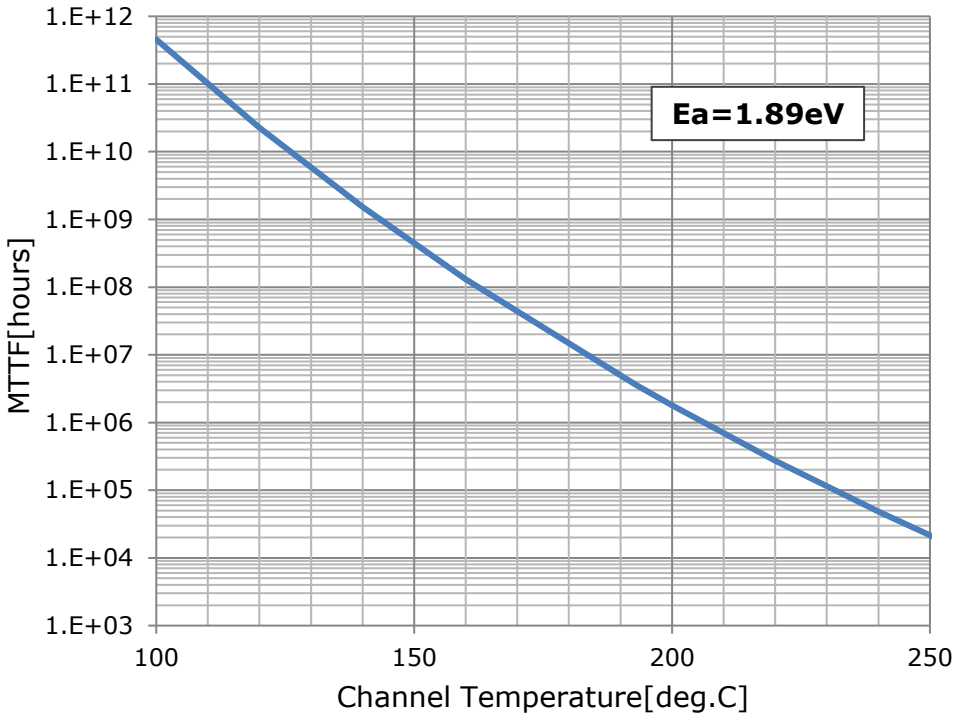




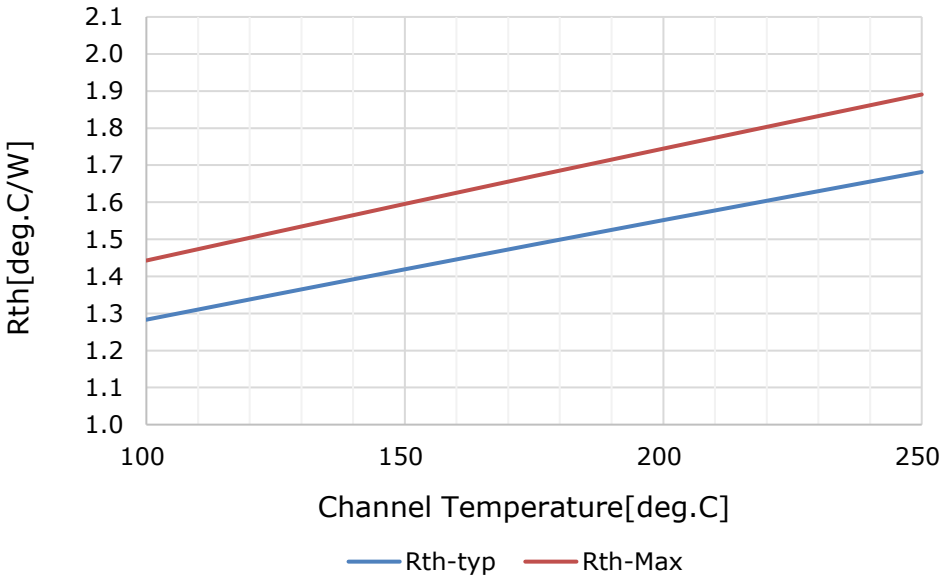
Bias Condition V_{DS}=24V, $I_{DS(DC)}$=2.6A
Rg = 51ohm

Freq.	S11		S21		S12		S22	
	mag	phase	mag	phase	mag	phase	mag	phase
6.2GHz	0.595	116.1	4.561	-40.8	0.041	-80.6	0.302	151.2
6.3GHz	0.600	105.5	4.489	-52.7	0.043	-95.3	0.308	138.0
6.4GHz	0.600	95.6	4.439	-64.6	0.045	-108.8	0.311	126.2
6.5GHz	0.596	86.1	4.430	-76.3	0.048	-122.0	0.314	114.3
6.6GHz	0.582	76.9	4.456	-88.2	0.050	-135.0	0.315	102.4
6.7GHz	0.559	67.6	4.508	-100.4	0.053	-147.8	0.316	90.5
6.8GHz	0.523	58.0	4.607	-113.1	0.055	-160.7	0.315	77.5
6.9GHz	0.475	48.0	4.714	-126.3	0.058	-173.9	0.317	63.4
7GHz	0.409	37.1	4.864	-140.3	0.062	172.4	0.322	47.4
7.1GHz	0.323	23.4	5.007	-155.5	0.065	157.6	0.329	29.1
7.2GHz	0.215	5.0	5.140	-172.3	0.068	141.3	0.343	8.1
7.3GHz	0.093	-35.8	5.202	169.6	0.070	123.9	0.363	-15.8
7.4GHz	0.114	-151.5	5.104	150.2	0.069	105.3	0.387	-41.8

- **MTTF vs. Tch**

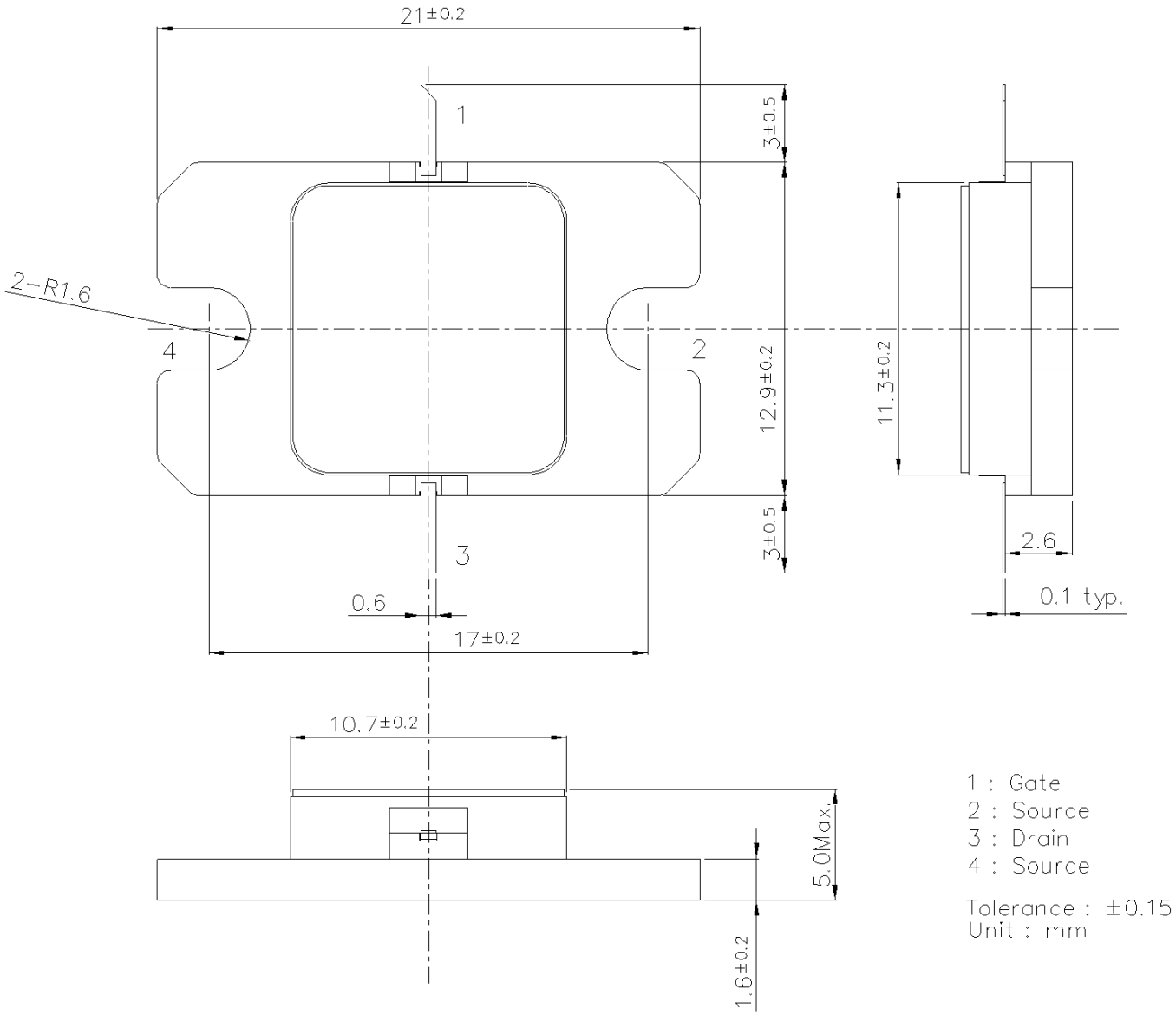


- **Rth vs. Tch**



Package Outline

Case Style : IBK



For Safety, Observe the Following Procedures Environmental Management

- Do not put this product into the mouth.
- Do not alter the form of this product into a gas, powder, or liquid through burning, crushing, or chemical processing as these by-products are dangerous to the human body if inhaled, ingested, or swallowed.
- Respect all applicable laws of the country when discarding this product.
  This product must be disposed in accordance with methods specified by applicable hazardous waste procedures.

Any information, such as descriptions of a function and examples of application circuits, in this document are presented solely as a reference for the purpose to show examples of operations and uses of Sumitomo Electric semiconductor device(s); Sumitomo Electric does not warrant the proper operation of the device(s) with respect to its use based on such information. When the user develops equipment incorporating the device(s) based on such information, they must assume full responsibility arising out of using such information. Sumitomo Electric assumes no liability for any damages whatsoever arising out of the use of the information.

Any information in this document, including descriptions of function and schematic diagrams, shall not be construed as a license for the use or exercise of any intellectual property right, such as patent right or copyright, or any other right of Sumitomo Electric or any third party nor does Sumitomo Electric warrant non-infringement of any third-party's intellectual property right or other right by using such information. Sumitomo Electric assumes no liability for any infringement of the intellectual property rights or other rights of third parties which would result from the use of information contained herein.

The products described in this document are designed, developed and manufactured as contemplated for general use, including, without limitation, ordinary industrial use, general office use, personal use, and household use, but are not designed, developed and manufactured as contemplated (1) for use accompanying fatal risks or dangers that, unless extremely high safety is secured, could have a serious effect to the public, and could lead directly to death, personal injury, severe physical damage or other loss (i.e., nuclear reaction control in nuclear facility, aircraft flight control, air traffic control, mass transport control, medical life support system, missile launch control in weapon system), or (2) for use requiring extremely high reliability (i.e., submersible repeater and artificial satellite).
Please note that Sumitomo Electric will not be liable to the user and/or any third party for any claims or damages arising from the aforementioned uses of the products.

Any semiconductor devices have an inherent chance of failure. You must protect against injury, damage or loss from such failures by incorporating safety design measures into your facility and equipment such as redundancy, fire protection, and prevention of excessive current levels and other abnormal operating conditions.

If any products described in this document represent goods or technologies subject to certain restrictions on export under the Foreign Exchange and Foreign Trade Law of Japan, the prior authorization of the Japanese government will be required for export of those products from Japan.

http://www.sedi.co.jp/

ATTENTION
Information in this document is subject to change without notice.